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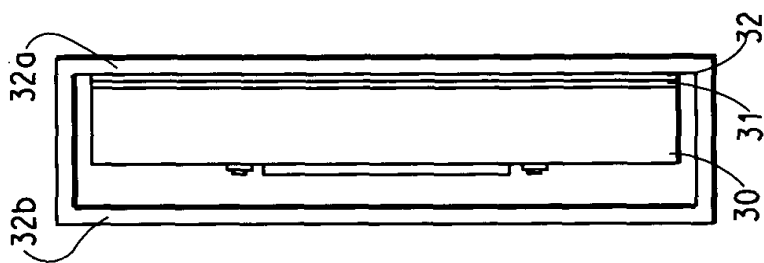


FIG. 3B

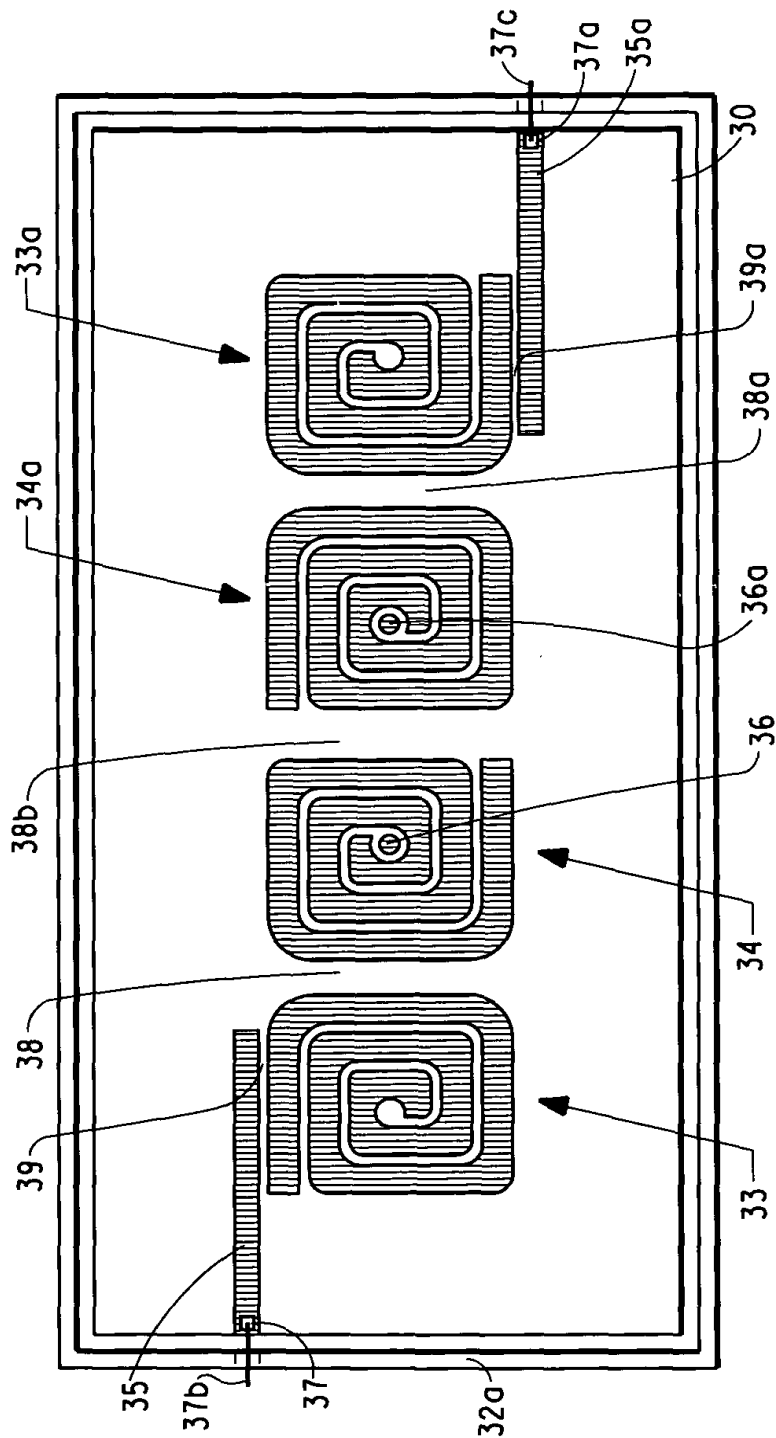


FIG. 3A

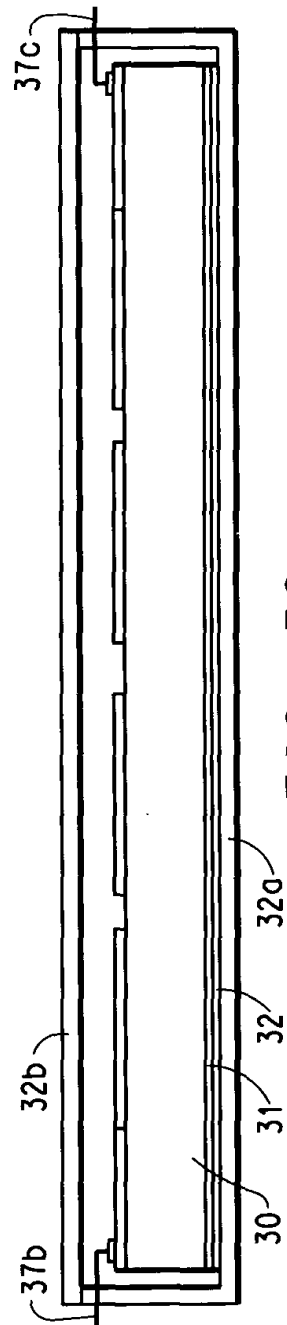


FIG. 3C

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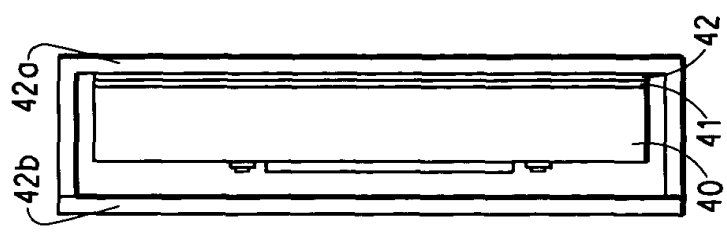


FIG. 4B

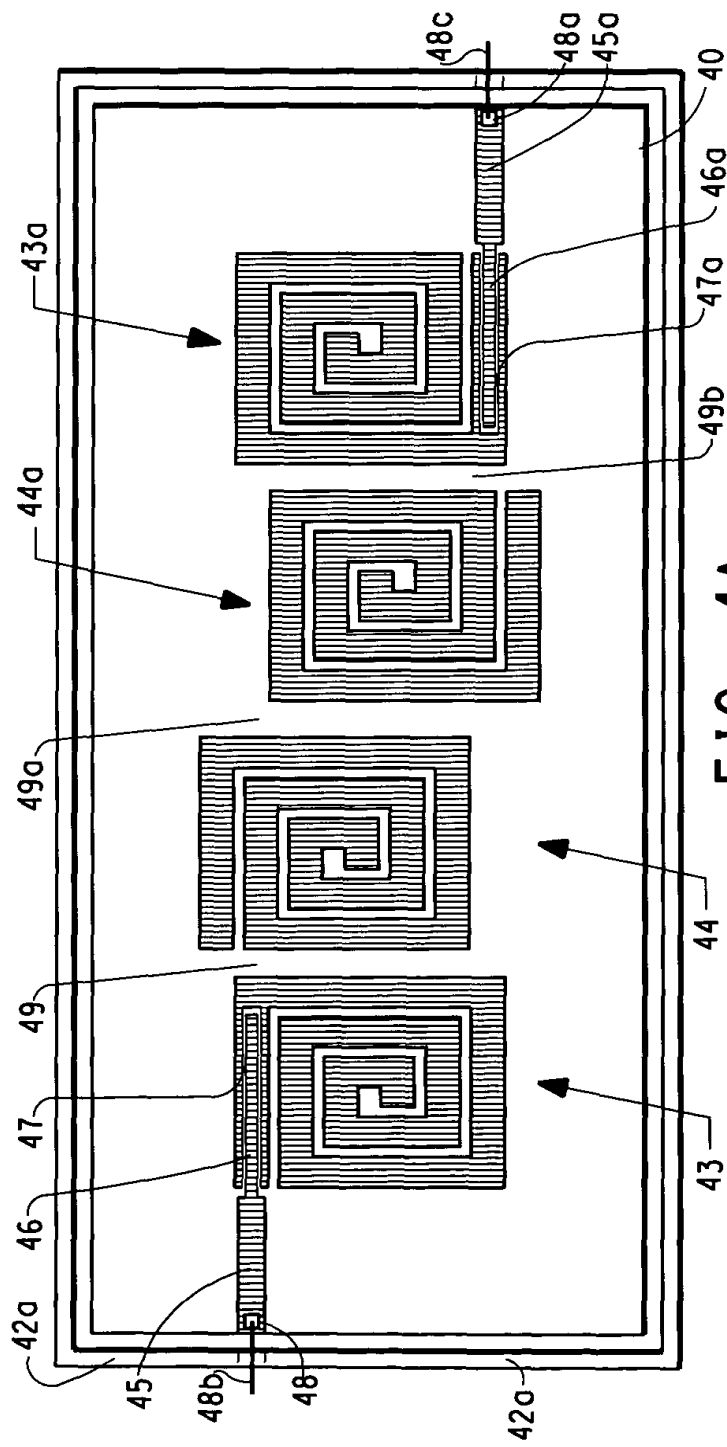


FIG. 4A

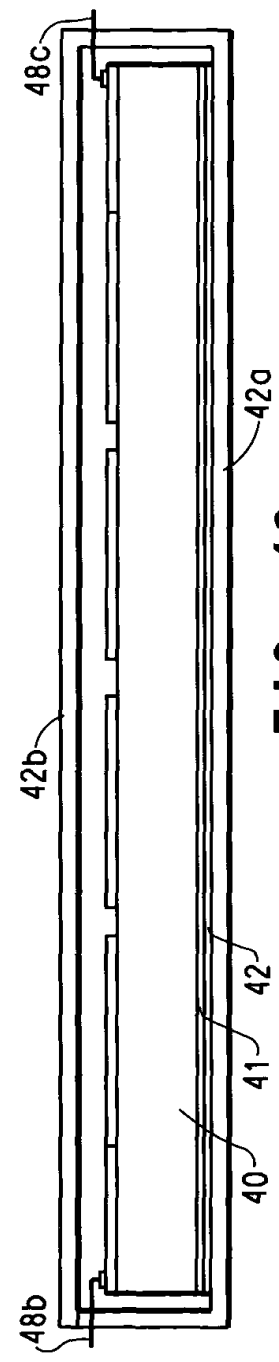


FIG. 4C

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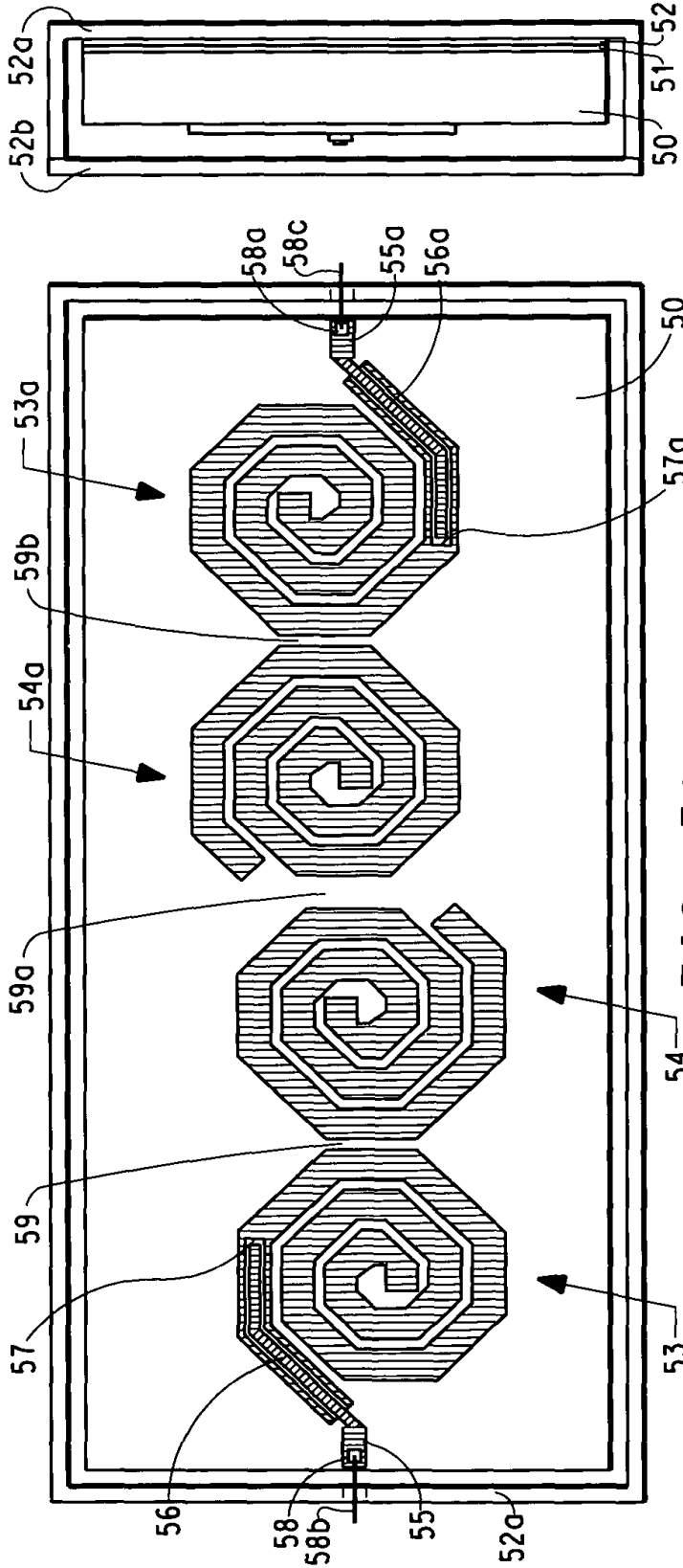


FIG. 5A

FIG. 5B

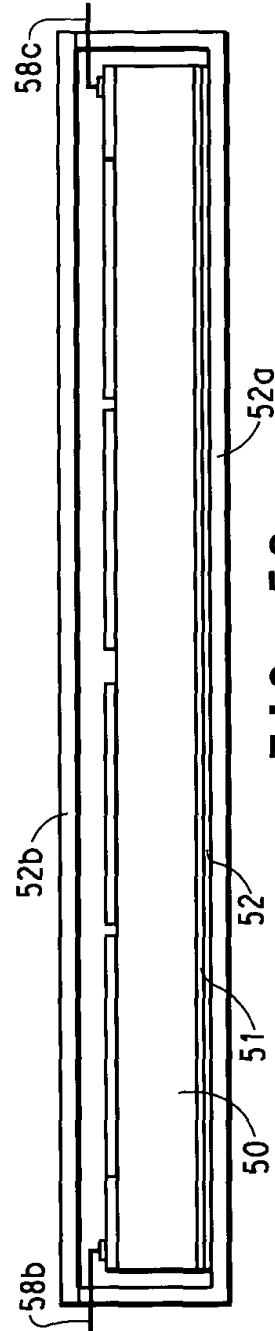


FIG. 5C



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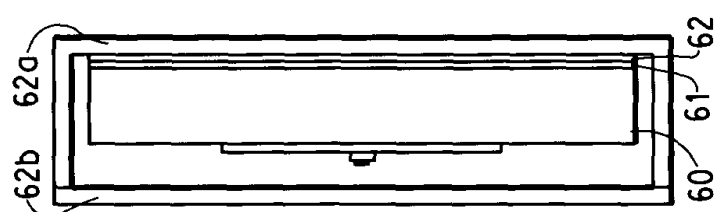


FIG. 6B

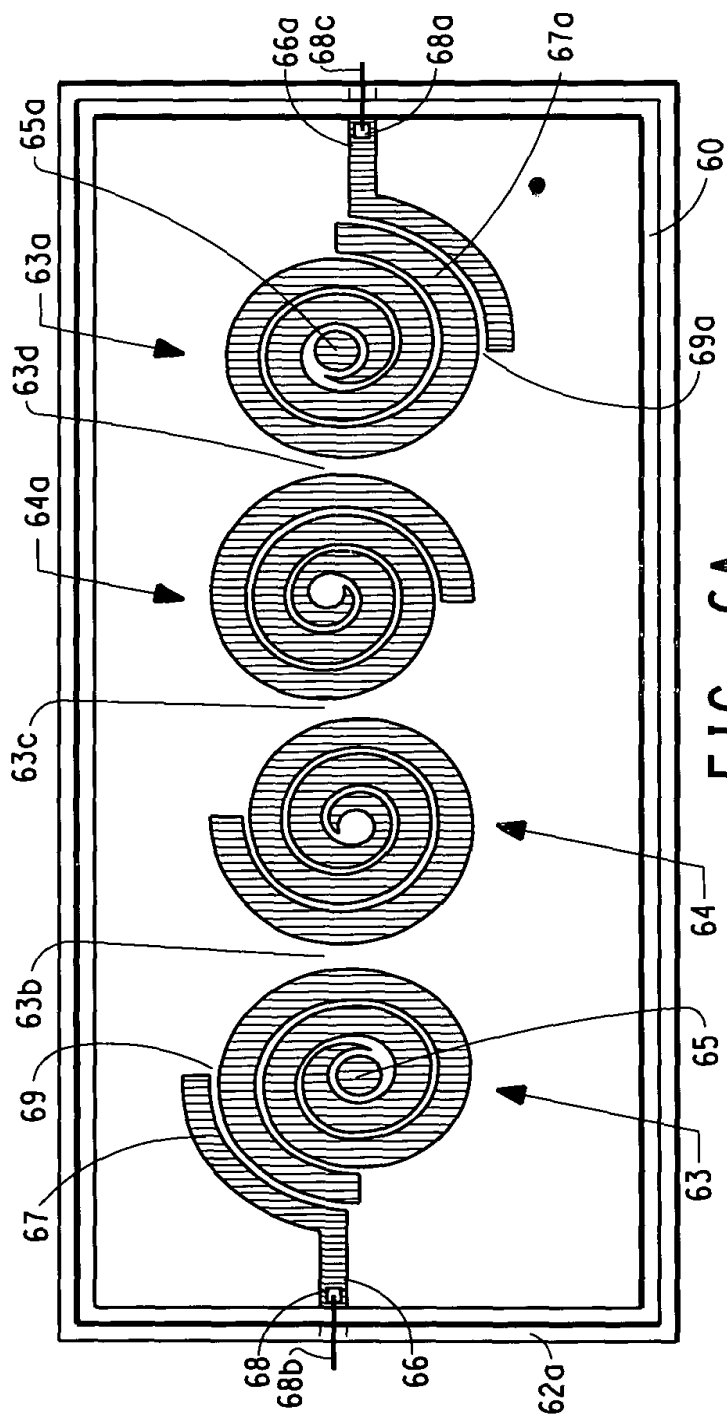


FIG. 6A

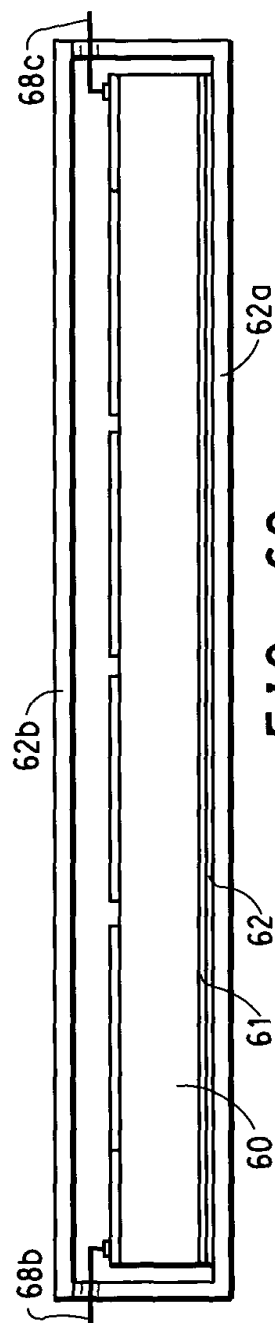


FIG. 6C



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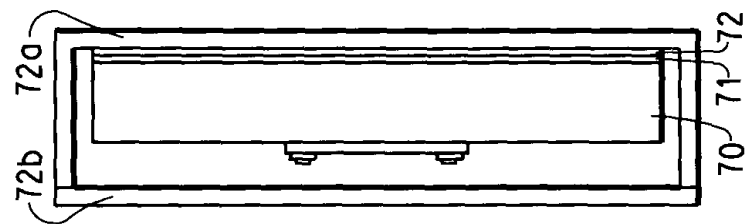


FIG. 7B

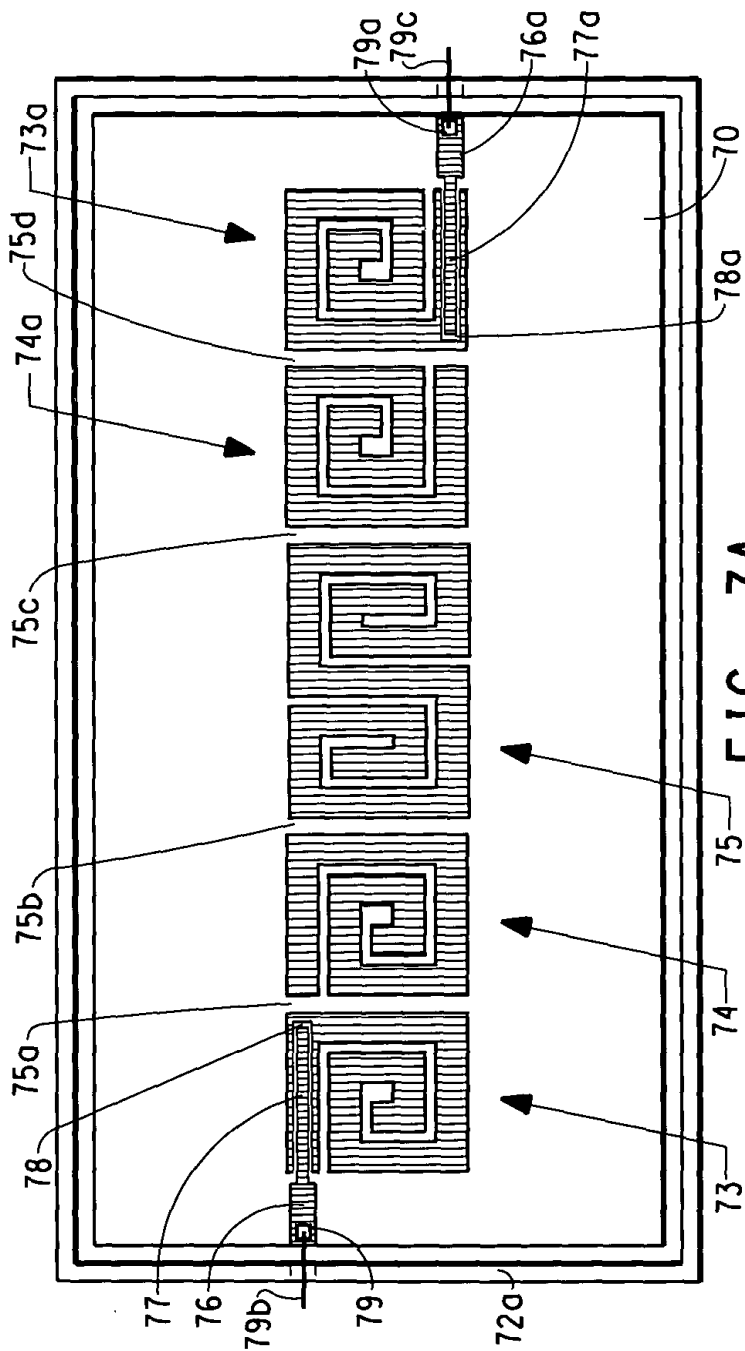


FIG. 7A

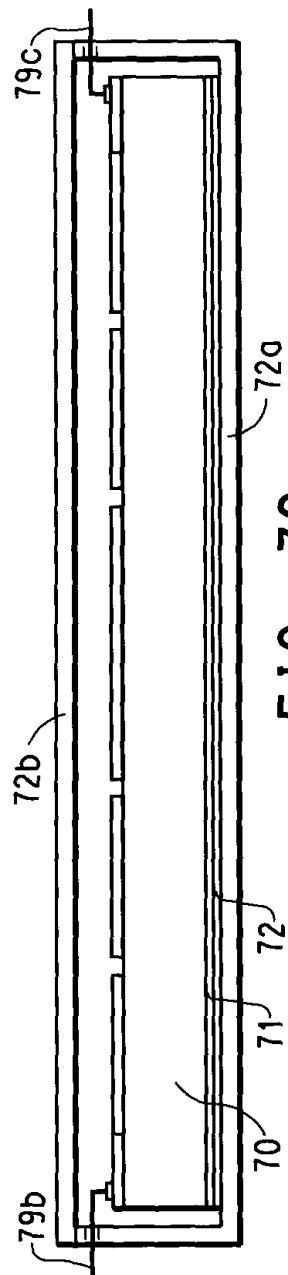


FIG. 7C



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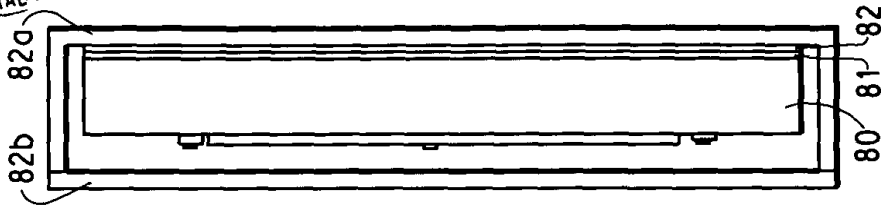


FIG. 8B

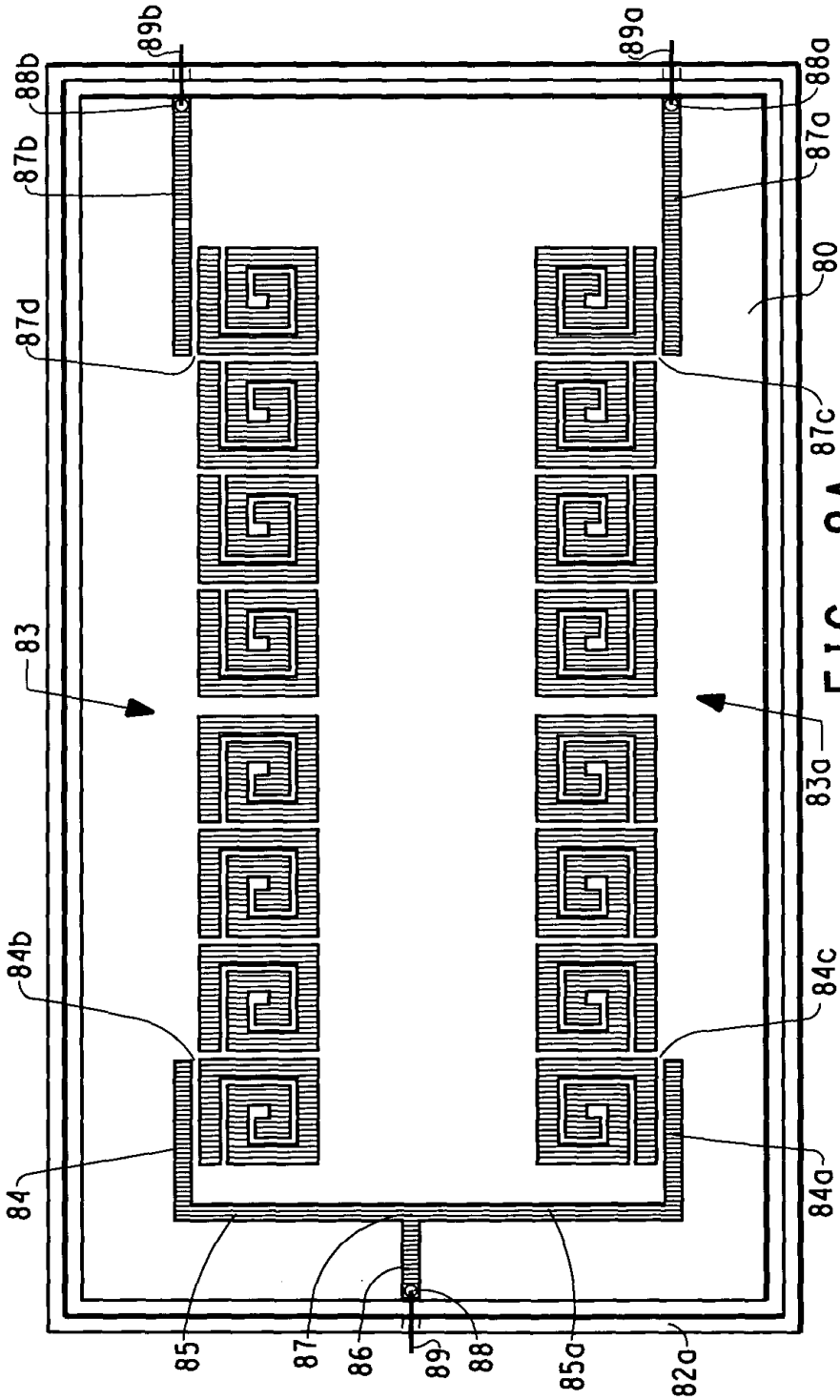


FIG. 8A

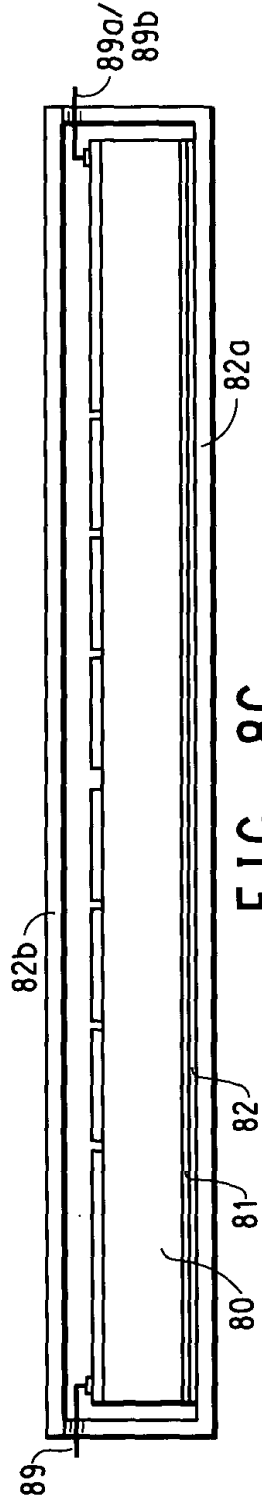


FIG. 8C



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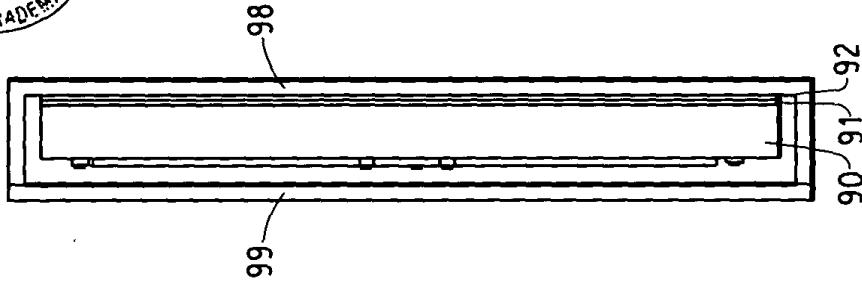


FIG. 9B

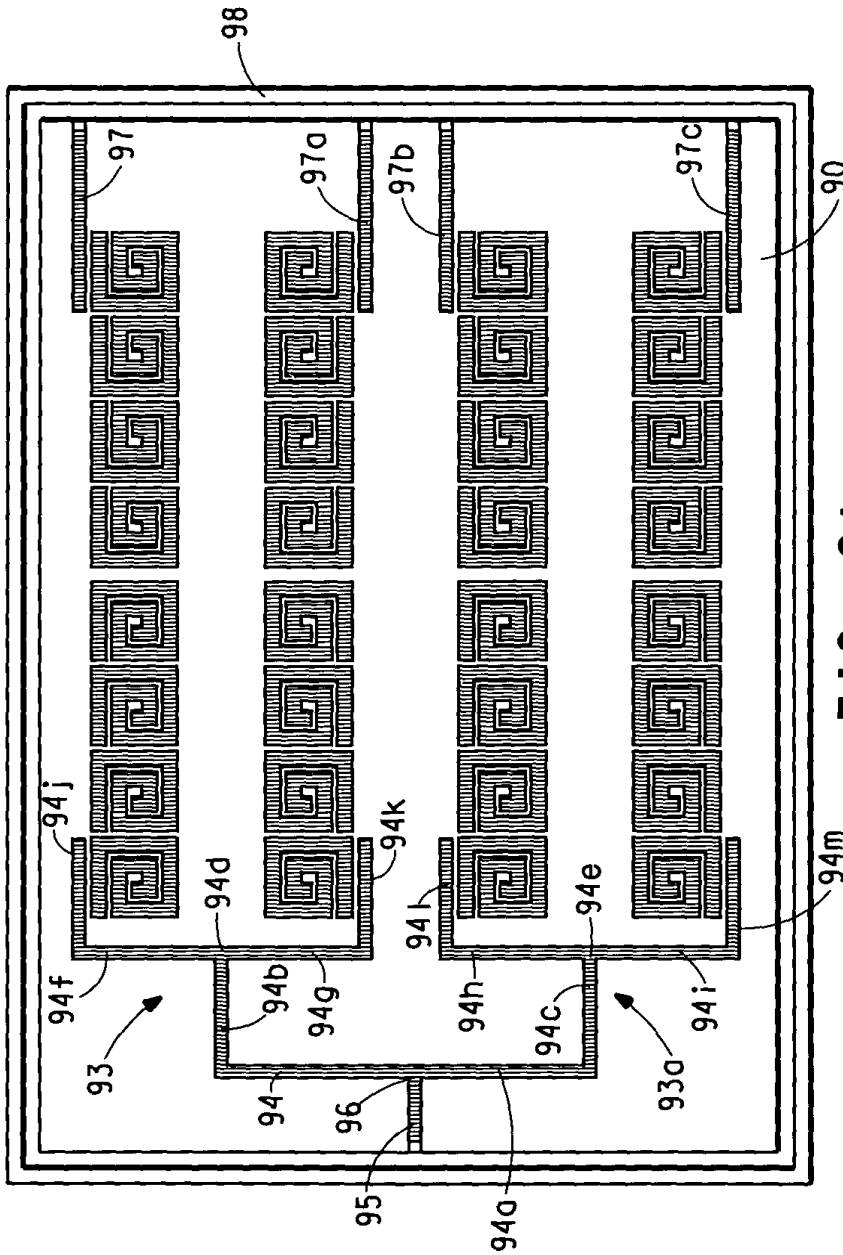


FIG. 9A

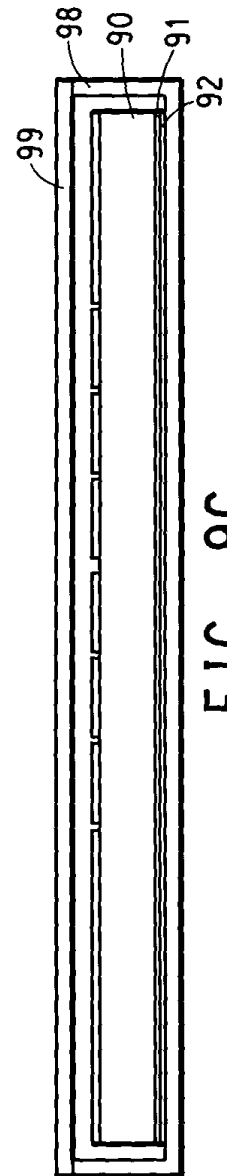


FIG. 9C



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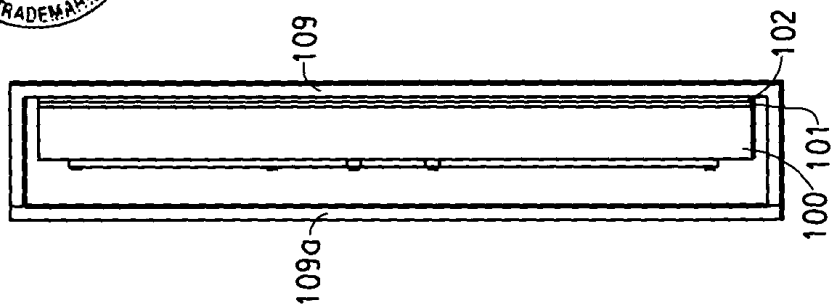


FIG. 10B

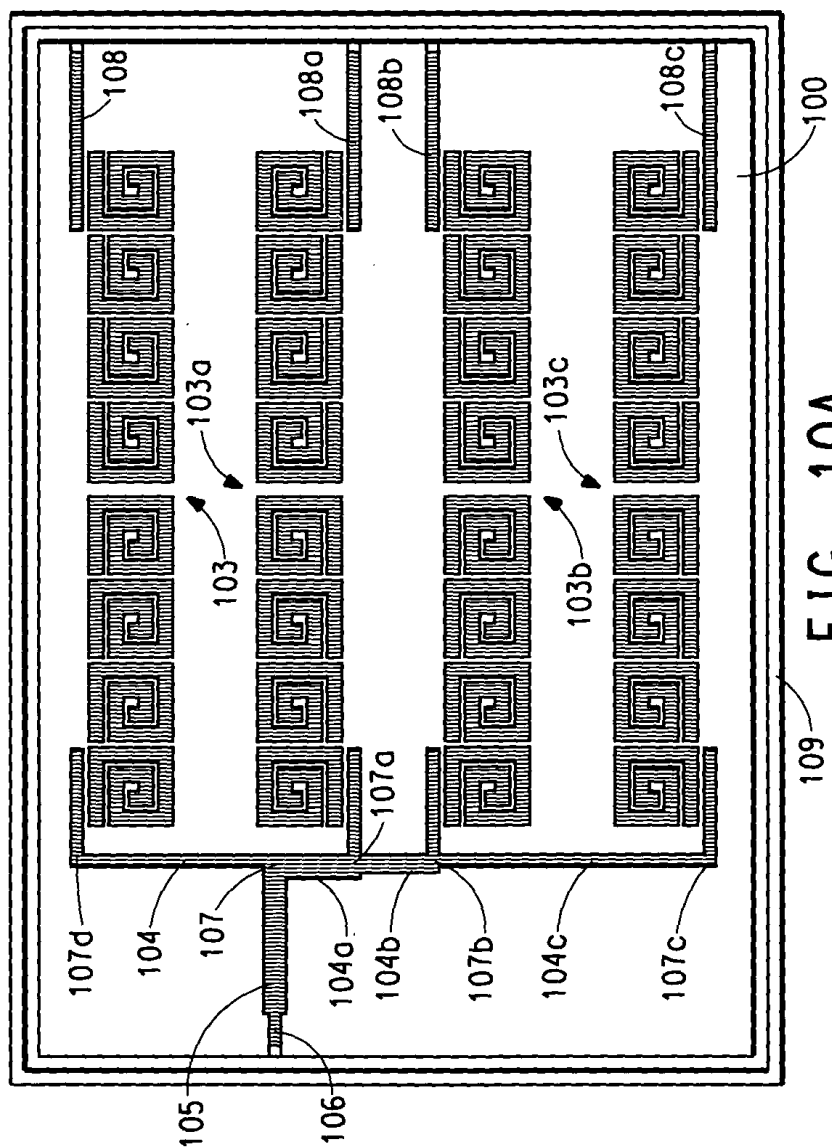


FIG. 10A

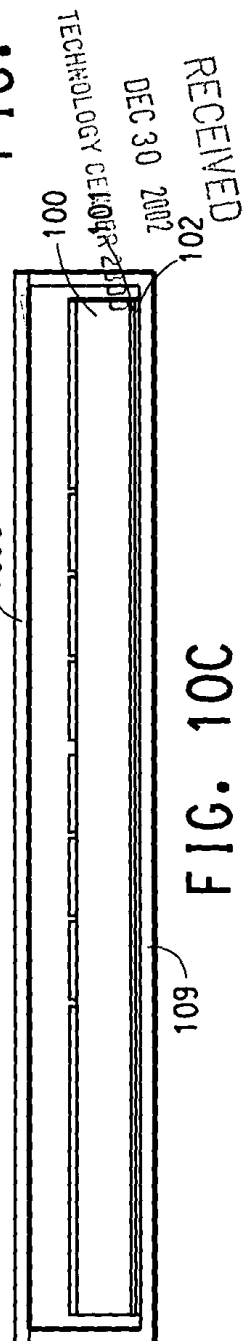


FIG. 10C

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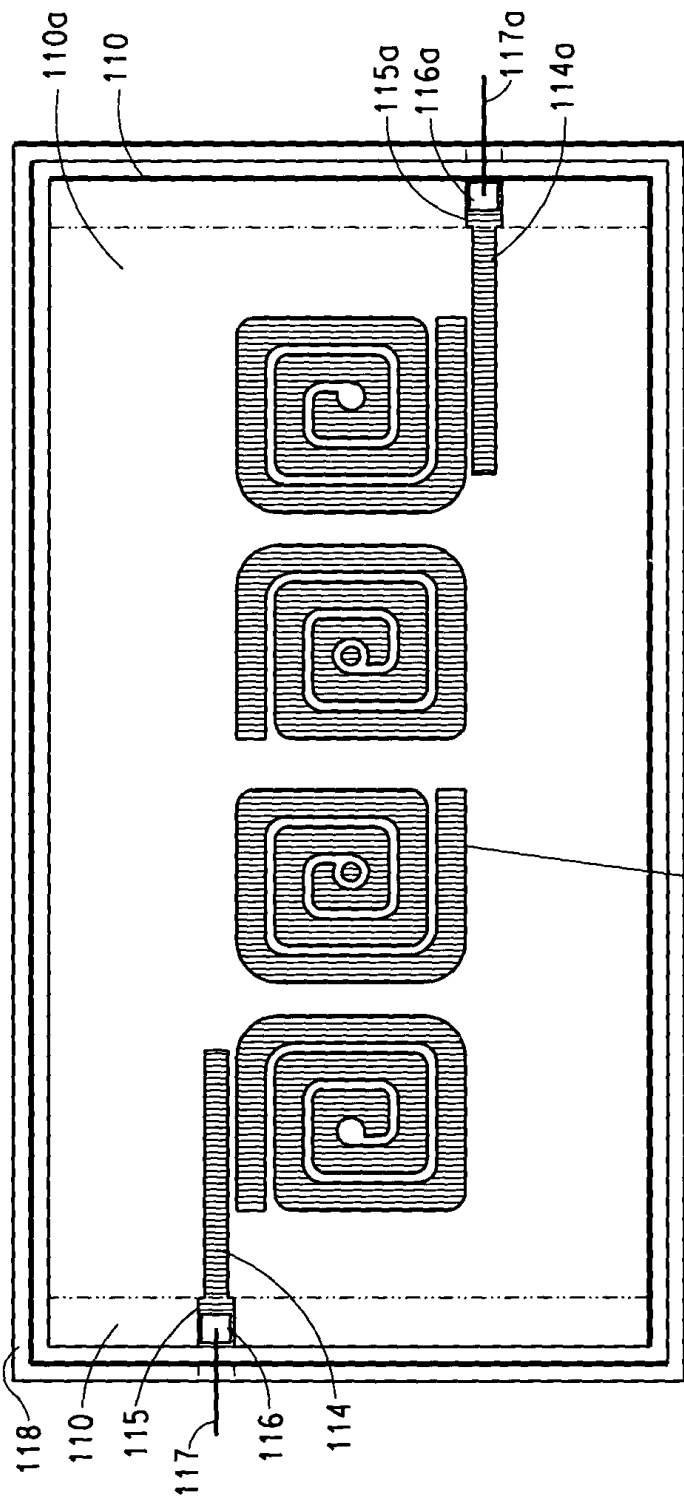


FIG. 11A

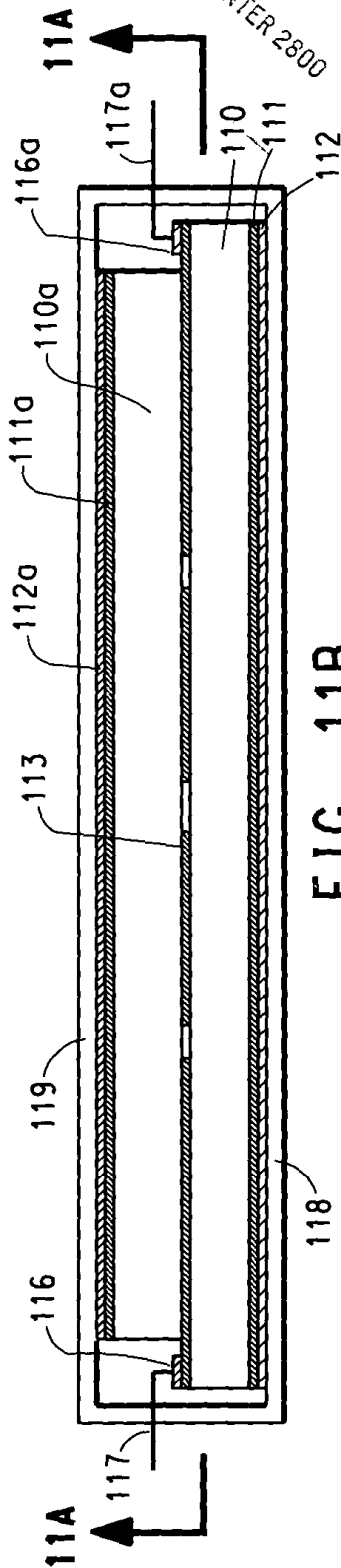


FIG. 11B

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